ABSTRACT

CHEMICAL MECHANICAL POLISHING APPARATUS WITH IMPROVED SUBSTRATE CARRIER HEAD AND METHOD OF USE

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An improved and new substrate carrier head for use in a CMP apparatus is described. The new substrate carrier head has a substrate retaining ring with embedded intersecting channels in the outer face. The embedded intersecting channels improve the circulation of polishing slurry to and from the polished substrate and polishing byproducts away from the polished substrate and thereby improve the polishing uniformity on the substrate.

(FIGURE 1A IS SUGGESTED FOR PUBLICATION)